



IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re the Application of  
Appln. No.: 10/747,862  
Filed: 12/29/2003  
For: Method for Fabricating a Lid for a  
Wafer Level Packaged Optical MEMS Device

Docket: TI-34210  
Art Unit: 2815  
Examiner: Clark, Sheila V.  
Conf. No.: 2777

**LETTER TO OFFICIAL DRAFTSPERSON**

December 22, 2004

Mail Stop Issue Fee  
Commissioner for Patents  
P.O. Box 1450  
Alexandria, VA 22313-1450

**MAILING CERTIFICATE UNDER 37 C.F.R. §1.8(A)**  
I hereby certify that the above correspondence is  
being deposited with the U.S. Postal Service as First  
Class Mail in an envelope addressed to: Commissioner  
for Patents, P.O. Box 1450, Alexandria, VA 22313-1450  
on the date below.

Sue Short

Date

Draftsperson:

Applicants submit five (5) sheets of formal drawings. Applicants believe that these drawings incorporate all required drawing changes imposed during the prosecution of this application. Applicants believe this application is now in condition for allowance.

Charge any necessary fee to the deposit account of Texas Instruments Incorporated, Account No. 20-0668.

Respectfully submitted,

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